

Dual N-Channel 60-V Power MOSFET

GENERAL DESCRIPTION

The LT4946 is the Dual N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching and low in-line power loss are needed in a very small outline surface mount package.

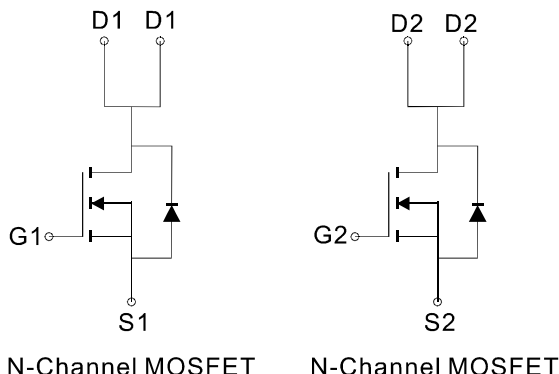
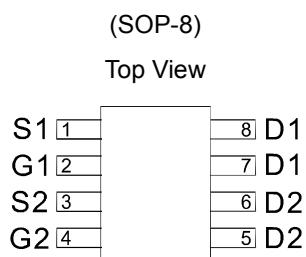
FEATURES

- $R_{DS(ON)} \leq 41m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 52m\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management
- DC/DC Converter
- LCD TV & Monitor Display inverter
- CCFL inverter

PIN CONFIGURATION



Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	V_{DSS}	60		V	
Gate-Source Voltage	V_{GSS}	± 20			
Continuous Drain Current (Tj=150°C)	I_D	$T_A=25^\circ C$	6.4	5	A
		$T_A=70^\circ C$	5.1	4	
Pulsed Drain Current	I_{DM}	30			
Continuous Source-Drain Diode Current	I_S	2			
Avalanche Current	I_{AS}	L=0.1mH	15		
Single-Pulse Avalanche Energy			E_{AS}	12	
Maximum Power Dissipation	P_D	$T_A=25^\circ C$	2.7	1.6	W
		$T_A=70^\circ C$	1.7	1	
Operating Junction & Storage Temperature Range	T_J	-55 to 150		°C	
Thermal Resistance-Junction to Ambient *	$R_{\theta JA}$	46	76	°C/W	
Thermal Resistance-Junction to Case *	$R_{\theta JC}$	43			

*The device mounted on 1in² FR4 board with 2 oz copper

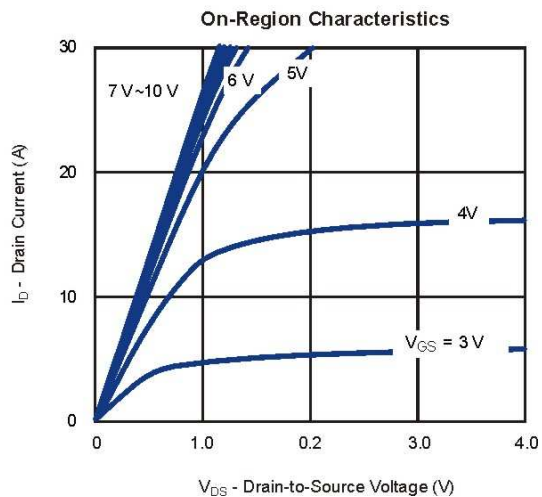
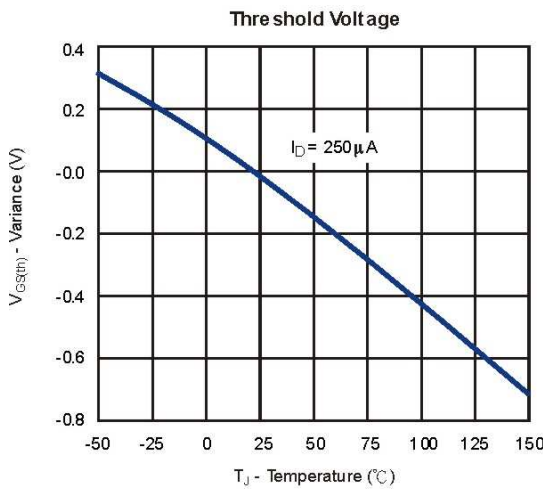
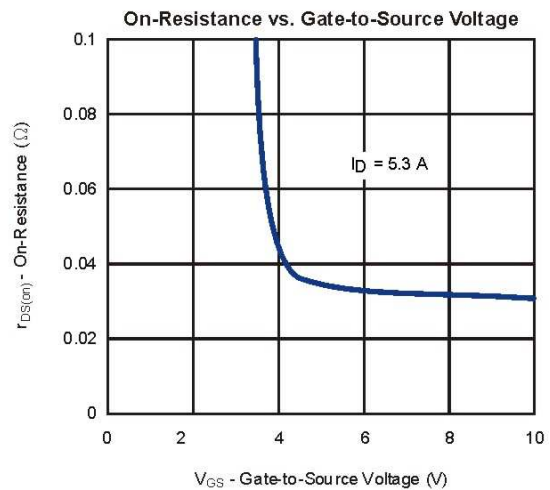
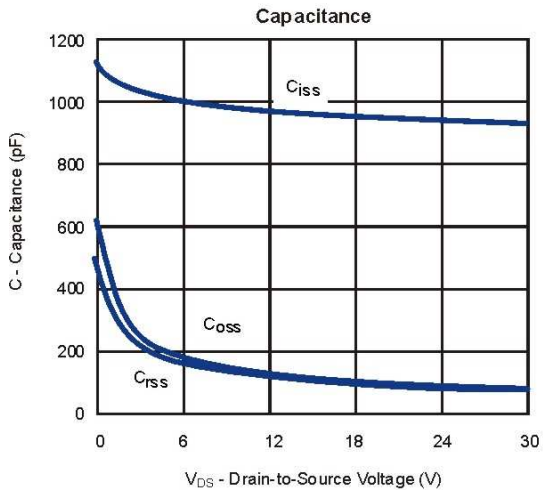
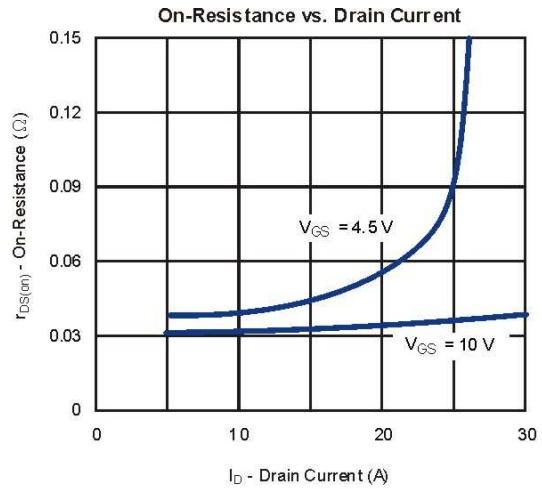
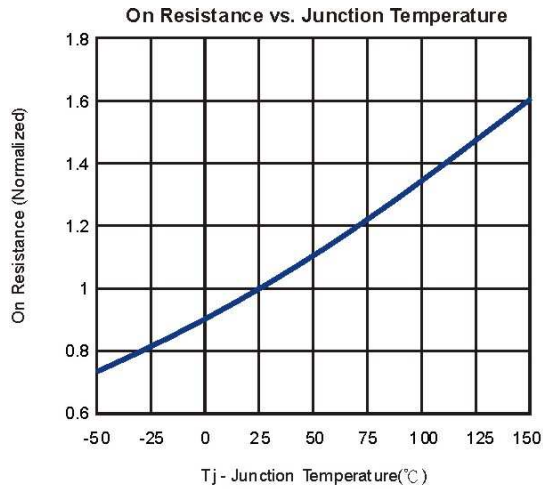
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Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
STATIC						
V_{DS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu A$	1.0	1.8	3.0	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1	μA
		$V_{DS}=60V, V_{GS}=0V$			10	
		$T_J=55^\circ\text{C}$				
$I_{D(ON)}$	On-State Drain Current ^a	$V_{DS}\geq 5V, V_{GS}=10V$	30			A
$R_{DS(ON)}$	Drain-Source On-Resistance ^a	$V_{GS}=10V, I_D=5.3A$		33	41	m Ω
		$V_{GS}=4.5V, I_D=4.7A$		40	52	
V_{SD}	Diode Forward Voltage	$I_S=2A$		0.8	1.2	V
DYNAMIC						
C_{iss}	Input capacitance	$V_{DS}=30V, V_{GS}=0V, f=1.0\text{MHz}$		940	1100	pF
C_{oss}	Output Capacitance			71		
C_{rss}	Reverse Transfer Capacitance			33		
Q_g	Total Gate Charge	$V_{DS}=30V, V_{GS}=10V, I_D=5.3A$		22	29	nC
				13.3	18	
Q_{gs}	Gate-Source Charge	$V_{DS}=30V, V_{GS}=5V, I_D=5.3A$		7.1		
Q_{gd}	Gate-Drain Charge			7.5		
R_g	Gate Resistance	$f=1\text{MHz}$		0.9		Ω
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, R_L=6.8\ \Omega$ $I_D=4.4A, V_{GEN}=10V$ $R_G=1\ \Omega$		14	18	ns
t_r	Turn-On Rise Time			26	33	
$t_{d(off)}$	Turn-Off Delay Time			41	52	
t_f	Turn-Off Fall Time			3.6	6	
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, R_L=6.8\ \Omega$ $I_D=4.4A, V_{GEN}=4.5V$ $R_G=1\ \Omega$		12	16	
t_r	Turn-On Rise Time			26	33	
$t_{d(off)}$	Turn-Off Delay Time			42	52	
t_f	Turn-Off Fall Time			3.8	7	

 Notes: a. Pulse test; pulse width $\leq 300\ \mu s$, duty cycle $\leq 2\%$

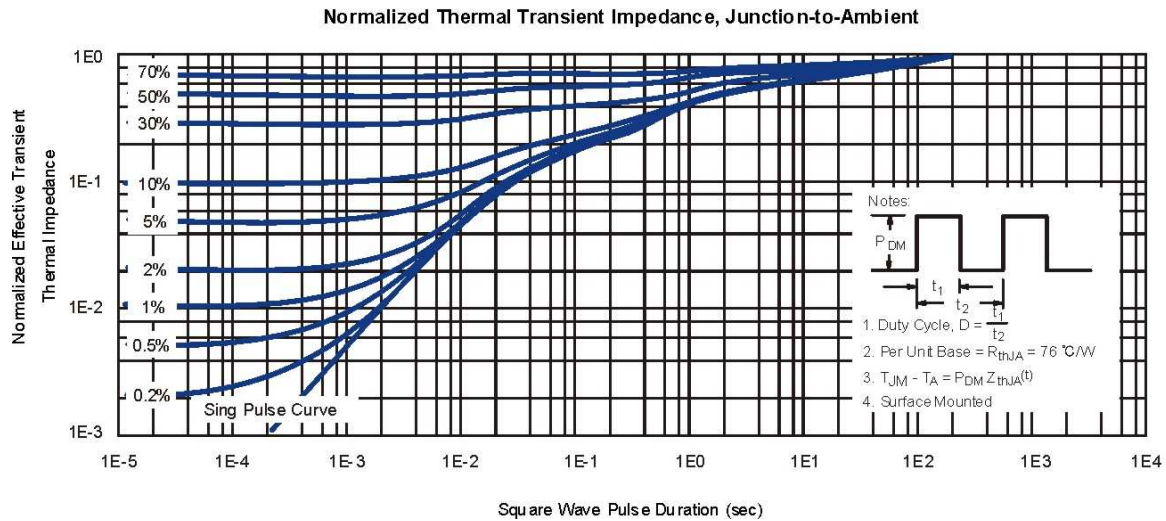
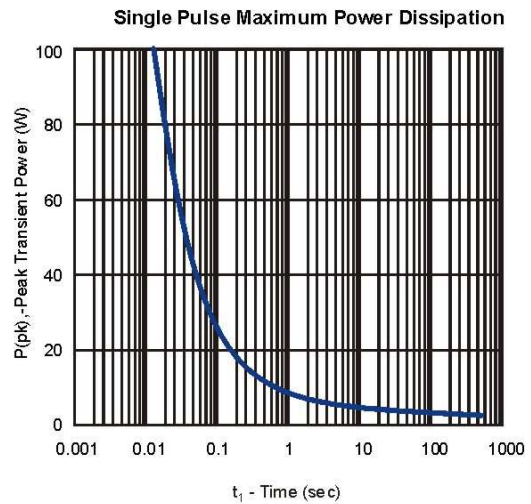
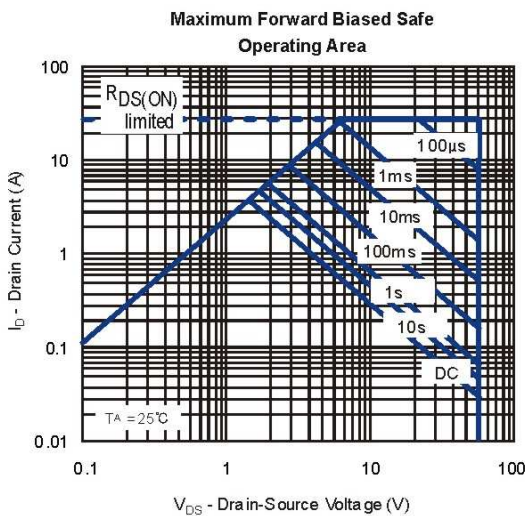
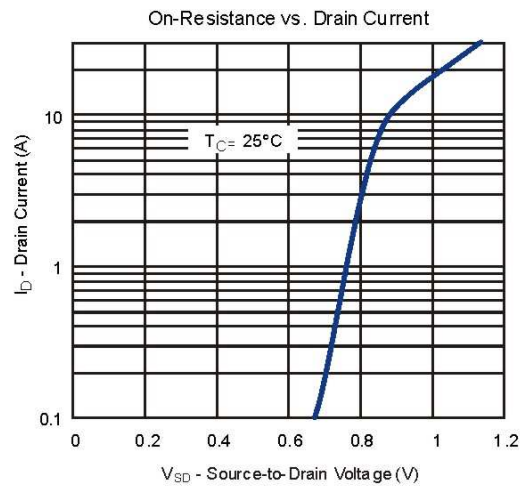
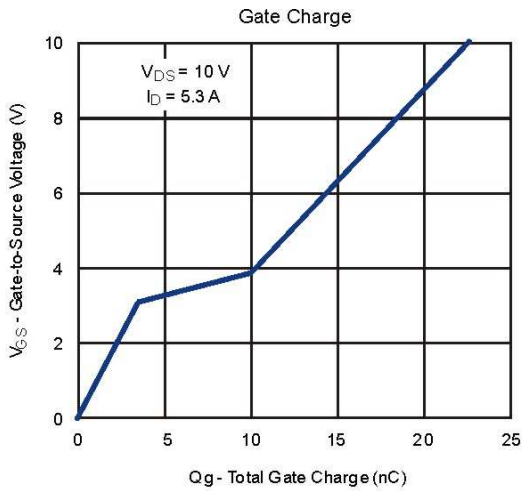
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Typical Characteristics (T_J =25°C Noted)



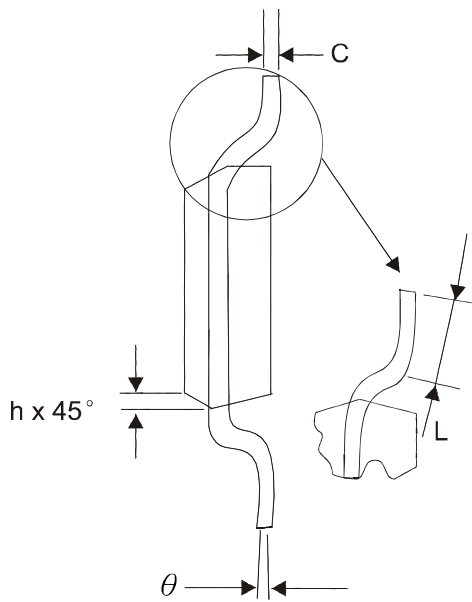
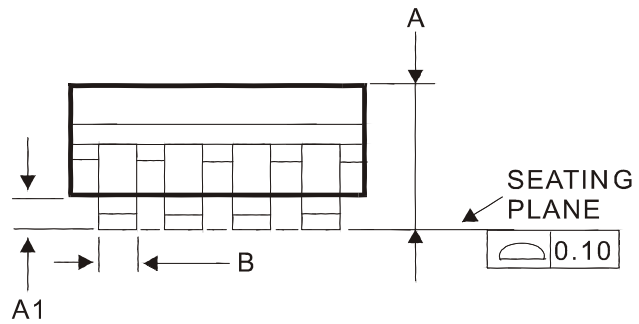
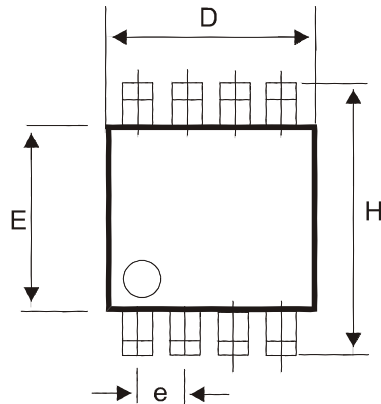
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SOP-8 Package Outline



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°